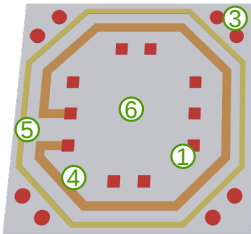
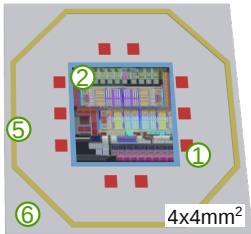


- ① Flip-Chip Pads
- ② Core System
- ③ Electrode Pads
- ④ Inductive Coil  $L_2$
- ⑤ Seal Ring
- ⑥ Silicon Substrate



Silicon Interposer



Active CMOS